IN THE CLAIMS

Please amend claim 1 as follows:

1. (Three Times Amended) A method of conductively cooling a heat-generating electronic component having an operating temperature range above normal room temperature and a first heat transfer surface disposable in thermal adjacency with a second heat transfer surface of a thermal dissipation member to define an interface therebetween, said method comprising the steps of:

(a) providing a thermally-conductive material which is form-stable at normal room temperature in a first phase and conformable in a flowable second phase to substantially fill said interface, said material having a transition temperature from said first phase to said second phase within the operating temperature range of said electronic component, and said material [consisting essentially of] comprising at least one resin or wax component [blended with] having a first melting temperature of from about 90-100°C, a second resin or wax component having a second melting temperature of from about 50-60°C, and at least one thermally-conductive filler;

(b) [forming] applying said material [into a self-supporting and free-standing film] in the form of a layer, [said layer consisting essentially of said material and having a thickness of from about 1-10 mils;

(c) applying said layer] to one of said heat transfer surfaces;

([d] c) disposing said heat transfer surfaces in thermal adjacency to define said interface; and

([e] d) energizing said electronic component effective to heat said layer to a temperature which is above said phase transition temperature.

Please amend claim 2 as follows:

2. (Amended) The method of claim 1 further comprising an additional step between steps ([d] c) and ([e] d) of applying an external force to at least one of said heat transfers defining said interface.

Please amend claim 5 as follows:

5. (Amended) The method of claim 1 wherein said self-supporting layer is [formed] applied in step (b) by coating a film of said material onto a surface of a release sheet, [and

wherein said layer is applied in step (c) by] adhering said film to one of said heat transfer and removing said release sheet to expose said film.

Please cancel claim 6.

Please amend claim 7 as follows:

7. (Amended) The method of claim [6] 1 wherein said material has a phase transition temperature of from about 60-80°C.

Please amend claim 8 as follows:

8. (Amended) The method of claim [6] 1 wherein said one or more thermally-conductive fillers is selected from the group consisting of boron nitride, alumina, aluminum oxide, aluminum nitride, magnesium oxide, zinc oxide, silicon carbide, beryllium oxide, and mixtures thereof.

Please amend claim 9 as follows:

9. (Three Times Amended) A thermally-conductive interface for interposition between a heat-generating electronic component having an operating temperature range above normal room temperature and a first heat transfer surface disposable in thermal adjacency with a second heat transfer surface of a thermal dissipation member, said interface comprising a [self-supporting and free-standing film] layer [having a thickness of from about 1-10 mils and consisting essentially] of a thermally-conductive material which is form-stable at normal room temperature in a first phase and substantially conformable in a flowable second phase to said interface surfaces, said material having a transition temperature from said first phase to said second phase within the operating temperature range of said electronic component, and said material [consisting essentially of at least one] comprising a first resin or wax component [blended with] having a first melting temperature of from about 90-100°C, a second resin or wax component having a second melting temperature of from about 50-60°C, and at least one thermally-conductive filler.

Please cancel claim 11.

Please amend claim 12 as follows:

12. (Amended) The interface of claim [11] 9 wherein said material has a phase transition temperature of from about 60-80°C.

Please amend claim 13 as follows:

13. (Amended) The interface of claim [11] 9 wherein said one or more thermally-conductive fillers is selected from the group consisting of boron nitride, alumina, aluminum oxide, aluminum nitride, magnesium oxide, zinc oxide, silicon carbide, beryllium oxide, and mixtures thereof.